

ABSTRACT:**A Process for Modifying Chip Assembly Substrates**

A method of modifying a chip assembly substrate comprising the steps of:

treating a selected area of the substrate to provide the selected area with a predetermined charge;

texturing the selected area of the substrate to affect the texture of the substrate surface;

depositing an electro-less plating catalyst, having an opposite charge to that of the predetermined charge, to at least the selected area of the substrate such that the catalyst remains affixed to the selected area of the substrate only; and

modifying the chip assembly substrate by electro-less plating the chip assembly substrate, only those areas to which the catalyst remains affixed being electro-less plated.

[FIGURE 3c]

This Sheet Has Been Replaced

